

AN 2000:342333 HCAPLUS
 DN 132:337980
 TI Lead-free solder of **tin**-aluminum-**indium**-**silver**
 alloy for low temperature use
 IN Domi, Shinjiro; Sakaguchi, Koichi; Nakagaki, Shigeki; Suganuma, Katsuaki
 PA Nippon Sheet Glass Co., Ltd., Japan
 SO Jpn. Kokai Tokkyo Koho, 5 pp.
 CODEN: JKXXAF

DT Patent
 LA Japanese

FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	JP 2000141078	A2	20000523	JP 1999-54716	19990302
PRAI	JP 1998-253852	A	19980908		
AB	The solder of Sn alloy contains Al 0.01-3.0, In 0.1-50, Ag 0.1-6.0, Cu 0-6.0, and Zn 0-10.0%. Oxide materials, e.g., glasses, ceramics, can be strongly bonded with the solder.				